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# FDP52N20 / FDPF52N20T

## N-Channel UniFET™ MOSFET

200 V, 52 A, ( $\sim 1\text{m}\Omega$ )

### Features

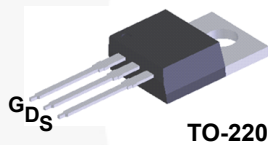
- $R_{DS(on)} = 41\text{ m}\Omega$  (Typ.) @  $V_{GS} = 10\text{ V}$ ,  $I_D = 26\text{ A}$
- Low Gate Charge (Typ. 49 nC)
- Low  $C_{RSS}$  (Typ. 66 pF)
- 100% Avalanche Tested
- RoHS Compliant

### Applications

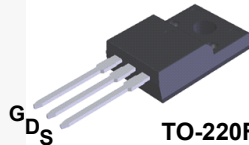
- PDP TV
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

### Description

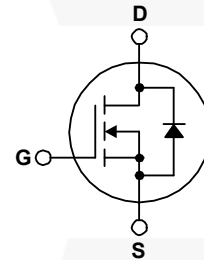
UniFET™ MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



TO-220



TO-220F



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

| Symbol         | Parameter  | FDP52N20                                   | FDPF52N20T | Unit             |   |
|----------------|--|--|------------|------------------|---|
| $V_{DSS}$      | Drain to Source Voltage  | 200  |            | V                |   |
| $V_{GSS}$      | Gate to Source Voltage   | $\pm 30$                                   |            | V                |   |
| $I_D$          | Drain Current  | - Continuous ( $T_C = 25^\circ\text{C}$ )  | 52         | 52*              | A |
|                |  | - Continuous ( $T_C = 100^\circ\text{C}$ ) | 33         | 33*              |   |
| $I_{DM}$       | Drain Current  | - Pulsed (Note 1)                          | 208        | 208*             | A |
| $E_{AS}$       | Single Pulsed Avalanche Energy (Note 2)                              | 2520                                       |            | mJ               |   |
| $I_{AR}$       | Avalanche Current (Note 1)   | 52   |            | A                |   |
| $E_{AR}$       | Repetitive Avalanche Energy (Note 1)                                 | 35.7                                       |            | mJ               |   |
| $dv/dt$        | Peak Diode Recovery $dv/dt$ (Note 3)                                 | 4.5  |            | V/ns             |   |
| $P_D$          | Power Dissipation  | ( $T_C = 25^\circ\text{C}$ )               | 357        | 38.5             | W |
|                |  | - Derate above $25^\circ\text{C}$          | 2.86       | 0.3              |   |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                              | -55 to +150                                |            | $^\circ\text{C}$ |   |
| $T_L$          | Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds | 300  |            | $^\circ\text{C}$ |   |

\*Drain current limited by maximum junction temperature

### Thermal Characteristics

| Symbol          | Parameter                                     | FDP52N20 | FDPF52N20T | Unit                      |
|-----------------|---|----------|------------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case, Max.    | 0.35     | 3.3        | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient, Max. | 62.5     | 62.5       |                           |

## Package Marking and Ordering Information

| Part Number | Top Mark   | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|------------|---------|----------------|-----------|------------|----------|
| FDP52N20    | FDP52N20   | TO-220  | Tube           | N/A       | N/A        | 50 units |
| FDPF52N20T  | FDPF52N20T | TO-220F | Tube           | N/A       | N/A        | 50 units |

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|--------|-----------|-----------------|------|------|------|------|
|--------|-----------|-----------------|------|------|------|------|

### Off Characteristics

|                                |   |   |     |     |           |                           |
|--------------------------------|---|---|-----|-----|-----------|---------------------------|
| $BV_{DSS}$                     | Drain to Source Breakdown Voltage         | $I_D = 250 \mu\text{A}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 25^\circ\text{C}$ | 200 | -   | -         | V                         |
| $\Delta BV_{DSS} / \Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$                  | -   | 0.2 | -         | $\text{V}/^\circ\text{C}$ |
| $I_{DSS}$                      | Zero Gate Voltage Drain Current           | $V_{DS} = 200 \text{ V}$ , $V_{GS} = 0 \text{ V}$                           | -   | -   | 1         | $\mu\text{A}$             |
|                                |   | $V_{DS} = 160 \text{ V}$ , $T_C = 125^\circ\text{C}$                        | -   | -   | 10        |                           |
| $I_{GSS}$                      | Gate to Body Leakage Current              | $V_{GS} = \pm 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$                        | -   | -   | $\pm 100$ | nA                        |

### On Characteristics

|              |                                      |  |     |       |       |          |
|--------------|--------------------------------------|--|-----|-------|-------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage               | $V_{GS} = V_{DS}$ , $I_D = 250 \mu\text{A}$    | 3.0 | -     | 5.0   | V        |
| $R_{DS(on)}$ | Static Drain to Source On Resistance | $V_{GS} = 10 \text{ V}$ , $I_D = 26 \text{ A}$ | -   | 0.041 | 0.049 | $\Omega$ |
| $g_{FS}$     | Forward Transconductance             | $V_{DS} = 40 \text{ V}$ , $I_D = 26 \text{ A}$ | -   | 35    | -     | S        |

### Dynamic Characteristics

|              |                               |  |   |      |      |    |
|--------------|-------------------------------|--|---|------|------|----|
| $C_{iss}$    | Input Capacitance             | $V_{DS} = 25 \text{ V}$ , $V_{GS} = 0 \text{ V}$<br>$f = 1 \text{ MHz}$    | - | 2230 | 2900 | pF |
| $C_{oss}$    | Output Capacitance            |  | - | 540  | 700  | pF |
| $C_{rfs}$    | Reverse Transfer Capacitance  |  | - | 66   | 100  | pF |
| $Q_{g(tot)}$ | Total Gate Charge at 10V      | $V_{DS} = 160 \text{ V}$ , $I_D = 52 \text{ A}$<br>$V_{GS} = 10 \text{ V}$ | - | 49   | 63   | nC |
| $Q_{gs}$     | Gate to Source Gate Charge    |  | - | 19   | -    | nC |
| $Q_{gd}$     | Gate to Drain "Miller" Charge |  | - | 24   | -    | nC |

### Switching Characteristics

|              |                     |  |   |     |     |    |
|--------------|---------------------|--|---|-----|-----|----|
| $t_{d(on)}$  | Turn-On Delay Time  | $V_{DD} = 100 \text{ V}$ , $I_D = 20 \text{ A}$<br>$R_G = 25 \Omega$ | - | 53  | 115 | ns |
| $t_r$        | Turn-On Rise Time   |  | - | 175 | 359 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time |  | - | 48  | 107 | ns |
| $t_f$        | Turn-Off Fall Time  | (Note 4)   | - | 29  | 68  | ns |

### Drain-Source Diode Characteristics

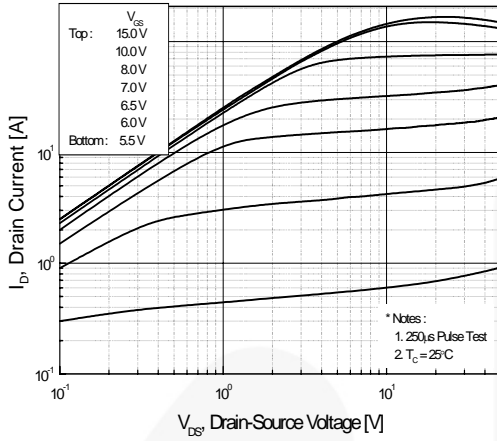
|          |  |  |   |     |     |               |
|----------|--|--|---|-----|-----|---------------|
| $I_S$    | Maximum Continuous Drain to Source Diode Forward Current | -  | - | 52  | A   |               |
| $I_{SM}$ | Maximum Pulsed Drain to Source Diode Forward Current     | -  | - | 204 | A   |               |
| $V_{SD}$ | Drain to Source Diode Forward Voltage                    | $V_{GS} = 0 \text{ V}$ , $I_{SD} = 52 \text{ A}$ | - | -   | 1.5 | V             |
| $t_{rr}$ | Reverse Recovery Time                                    | $V_{GS} = 0 \text{ V}$ , $I_{SD} = 52 \text{ A}$ | - | 162 | -   | ns            |
| $Q_{rr}$ | Reverse Recovery Charge                                  | $di/dt = 100 \text{ A}/\mu\text{s}$              | - | 1.3 | -   | $\mu\text{C}$ |

#### Notes:

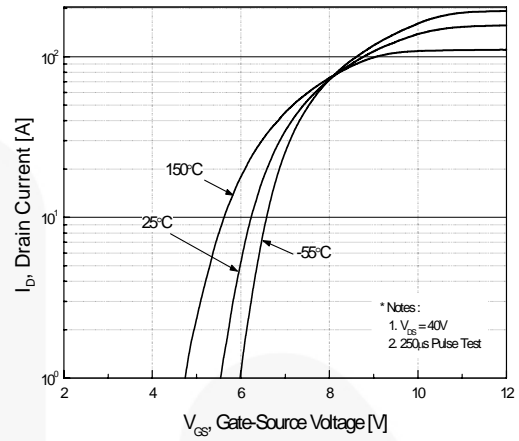
- 1: Repetitive rating: pulse-width limited by maximum junction temperature.
- 2:  $L = 1.4 \text{ mH}$ ,  $I_{AS} = 52 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
- 3:  $I_{SD} \leq 52 \text{ A}$ ,  $di/dt \leq 200 \text{ A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , starting  $T_J = 25^\circ\text{C}$ .
- 4: Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

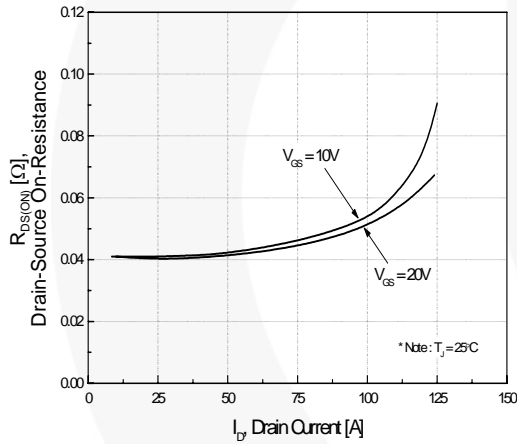
**Figure 1. On-Region Characteristics**



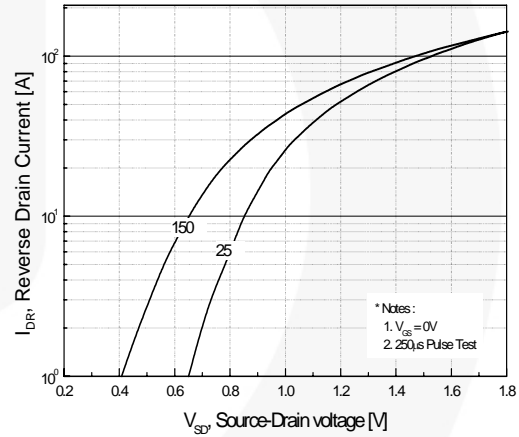
**Figure 2. Transfer Characteristics**



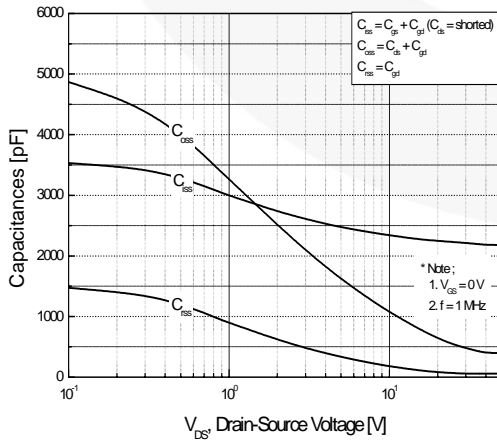
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



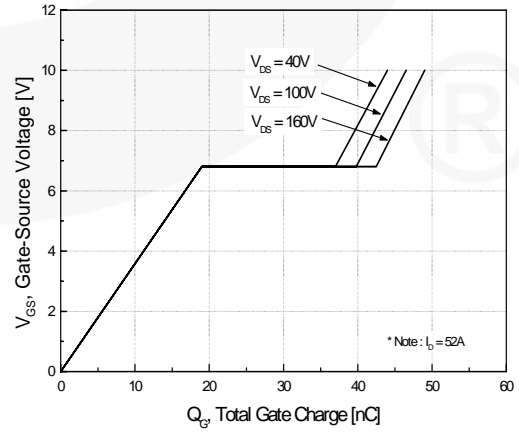
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

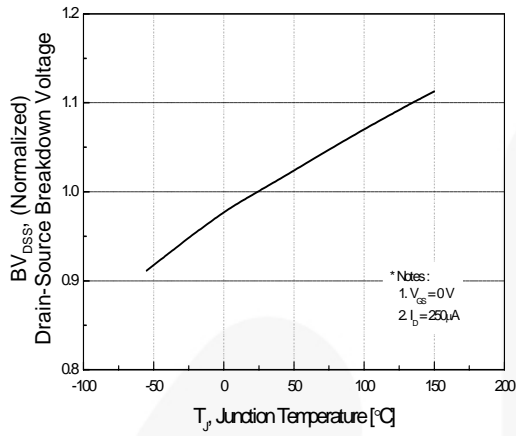


**Figure 6. Gate Charge Characteristics**

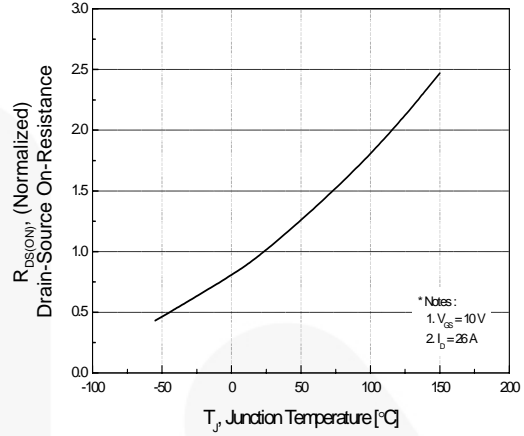


**Typical Performance Characteristics** (Continued)

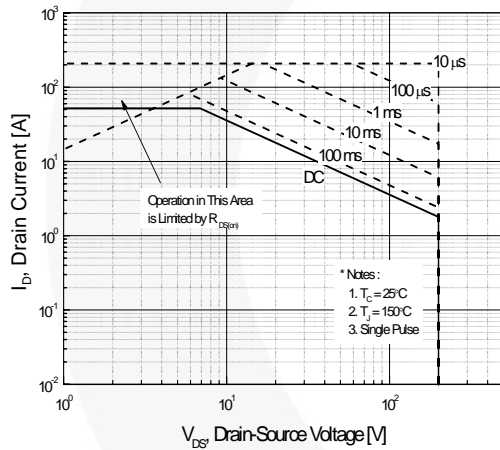
**Figure 7. Breakdown Voltage Variation vs. Temperature**



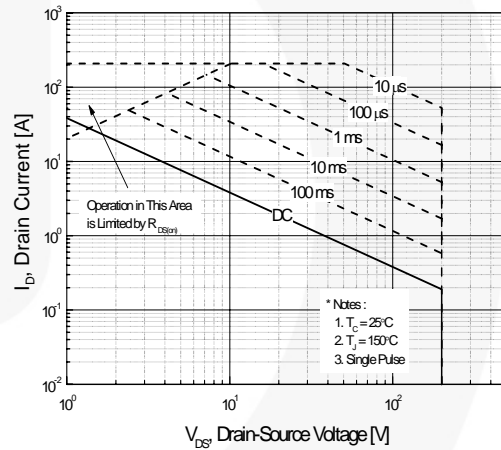
**Figure 8. On-Resistance Variation vs. Temperature**



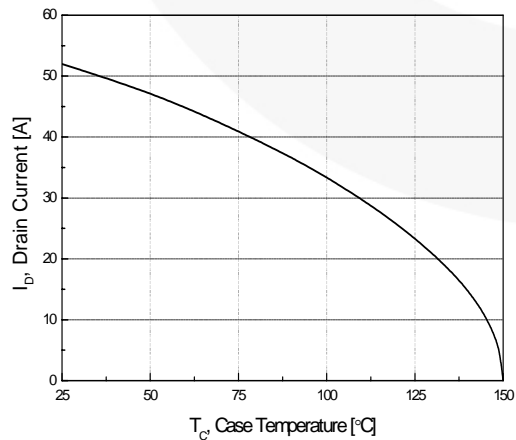
**Figure 9-1. Maximum Safe Operating Area - FDP52N20**



**Figure 9-2. Maximum Safe Operating Area - FDPF52N20T**

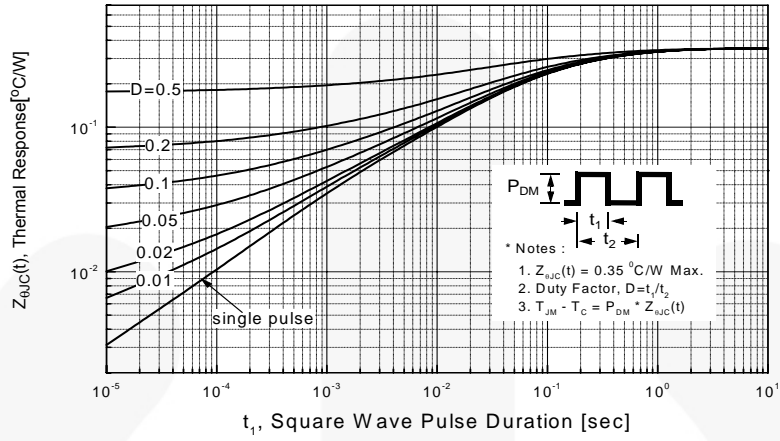


**Figure 10. Maximum Drain Current**

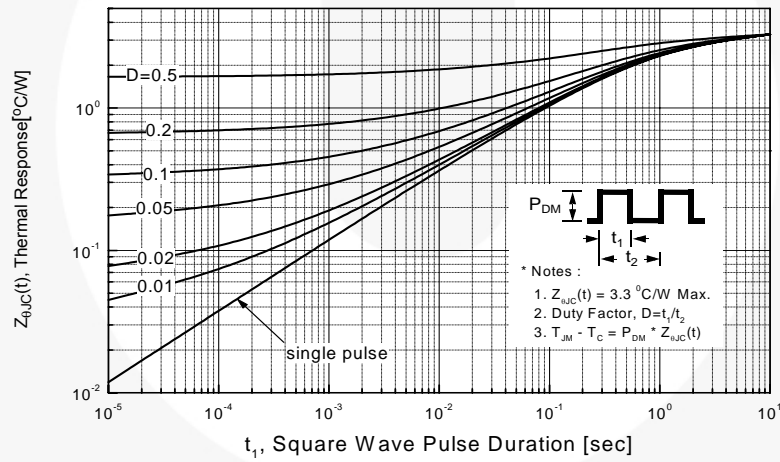


**Typical Performance Characteristics** (Continued)

**Figure 11-1. Transient Thermal Response Curve - FDP52N20**



**Figure 11-2. Transient Thermal Response Curve - FDPF52N20T**



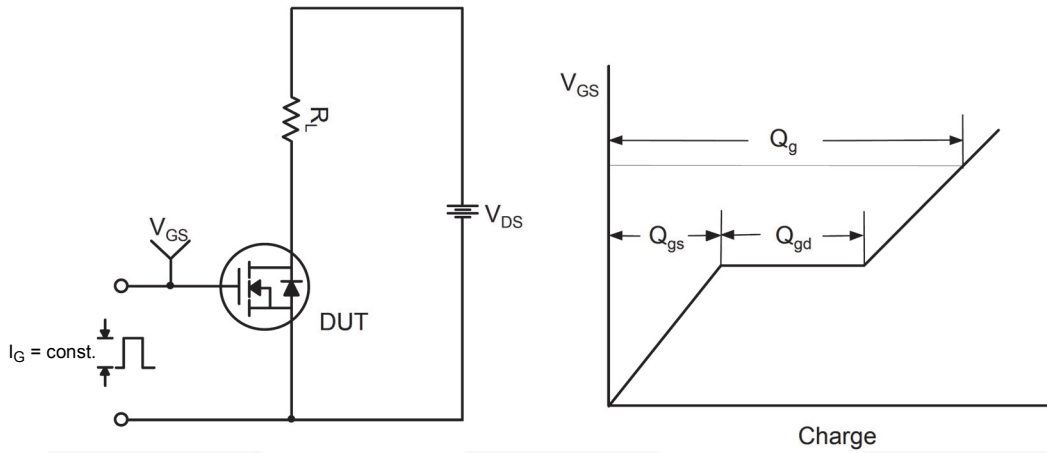


Figure 12. Gate Charge Test Circuit & Waveform

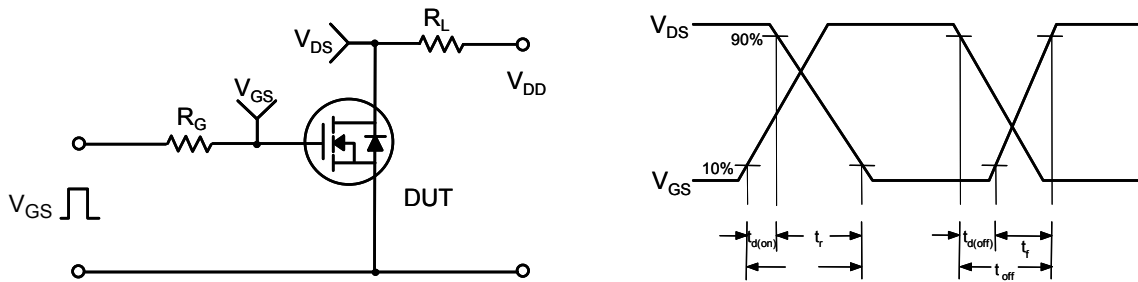


Figure 13. Resistive Switching Test Circuit & Waveforms



Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

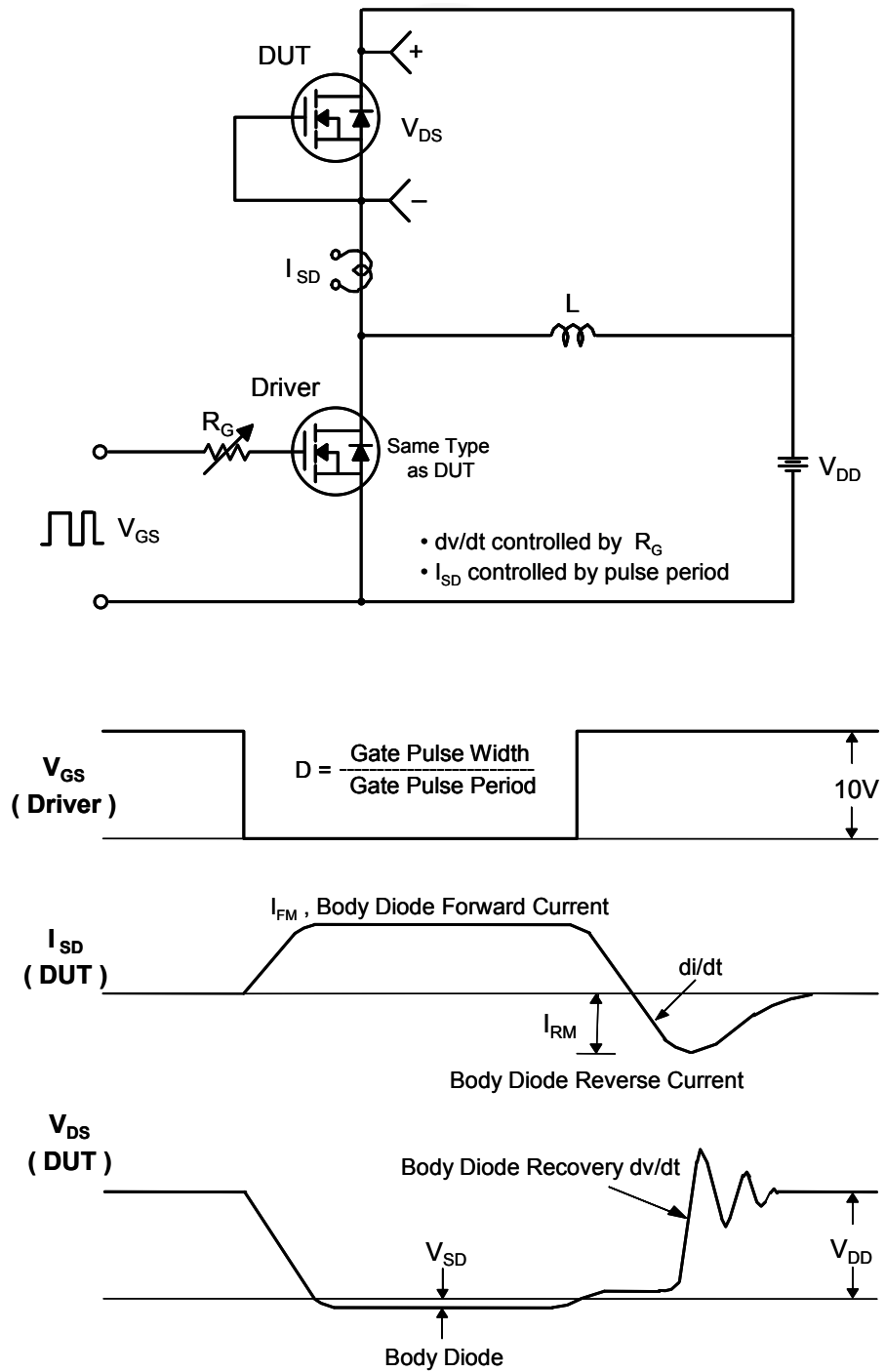


Figure 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms



## Mechanical Dimensions



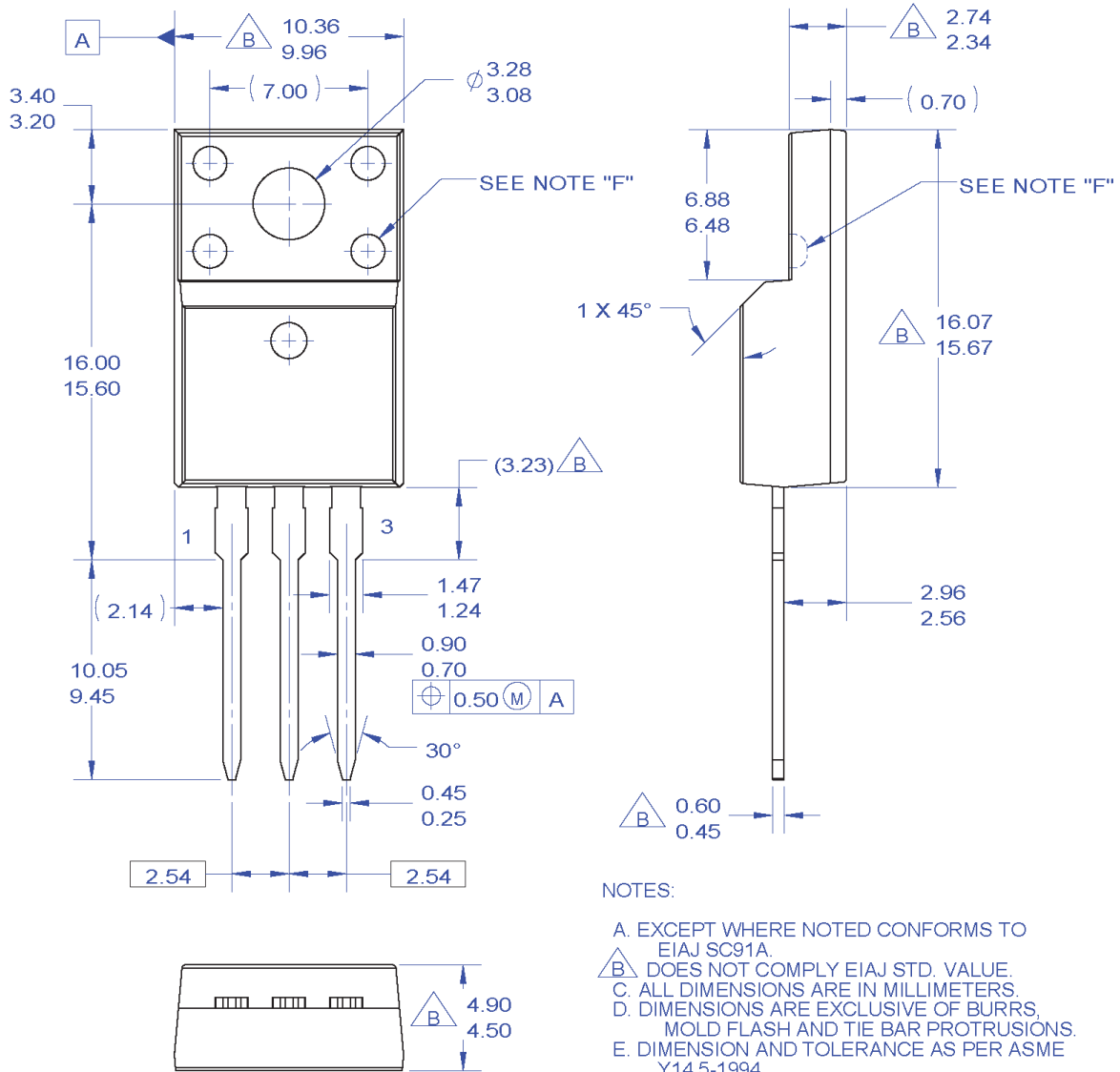
**Figure 16. TO-220, Molded, 3-Lead, Jedec Variation AB**

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## Mechanical Dimensions



### NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B. DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. OPTION 1 - WITH SUPPORT PIN HOLE.  
OPTION 2 - NO SUPPORT PIN HOLE.
- G. DRAWING FILE NAME: TO220M03REV3

**Figure 17. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead**

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| EfficientMax™            | MICROCOUPLER™                                   |                            | TRUECURRENT®*    |
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| <b>F</b> ®               | MicroPak™                                       |                            | <b>µ</b> SerDes™ |
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| FACT®                    | mWSaver®  |                            | VCX™             |
| FAST®                    | OptoHiT™  |                            | VisualMax™       |
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